

NEW



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Improve
Quality



Reduce
FQC Labor



Final Testing
Data Integration

■ 在检测的同时可自动分类缺陷

通过AI全自动分选・判定同步处理实现完全无人化
AI Real-time Defect Classification: Human-Free Sorting Achieved

■ 高灵活性：支持各检测项目独立操作与整合操作

Flexibility and easy to adjust for AVI only and 3D only or AVI+3D inspection

■ 在保持高精度与高分辨率的同时优化成本

实现高分辨率检测与高精度测量性能的完美结合
High Precision & Resolution

■ 全面支持大型基板与高密度凸块

可灵活应对更大尺寸基板、大量凸块、微小直径凸块及窄间距需求，
同时兼容各种凸块形状与方向的多样化要求
Fully Compatible with Large Panels & High-Density Bumps.

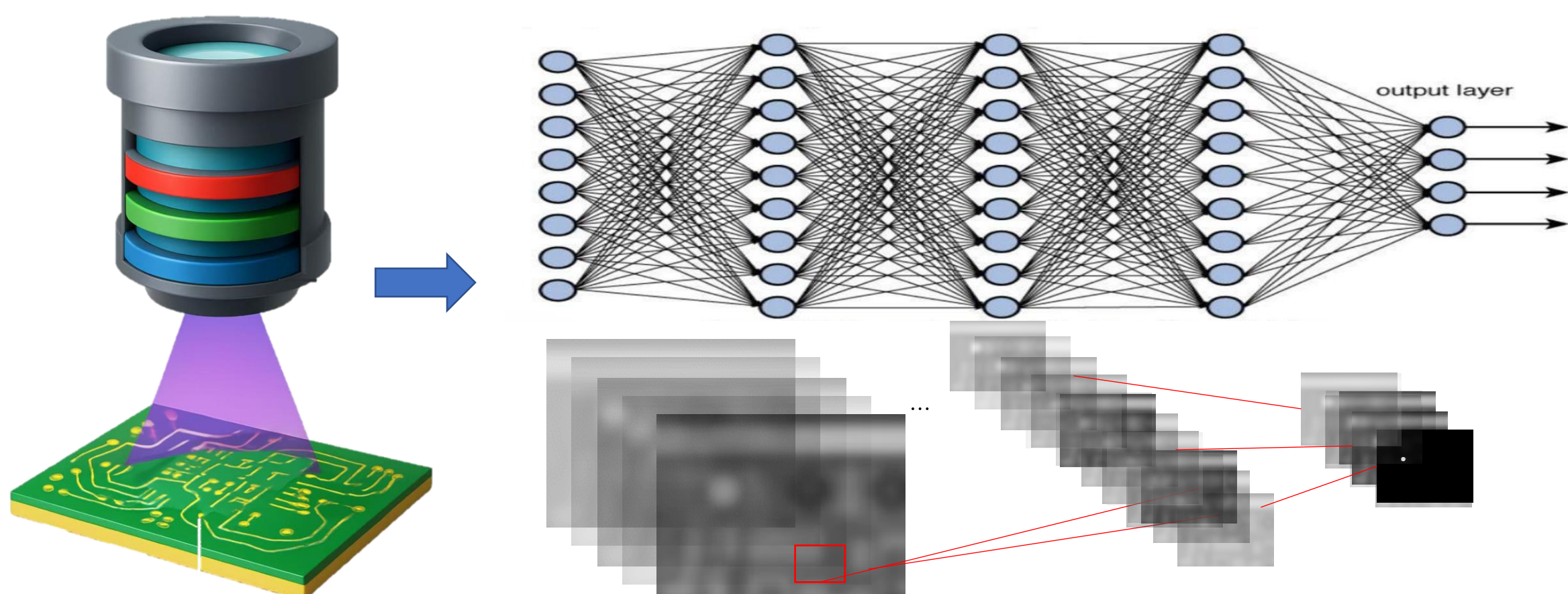
■ 搭载尖端软件与算法

配备多核及先进封装专用TTV/STV测量等强大分析功能
Equipped with Cutting-Edge Software and Algorithms.

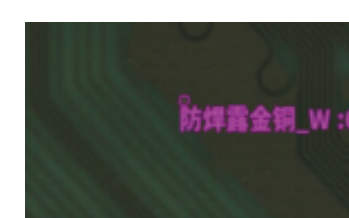
AI + Computer Vision integrated hardware/software system | Fully automated color inspection solution

AI+传统算法实现缺陷自动分类

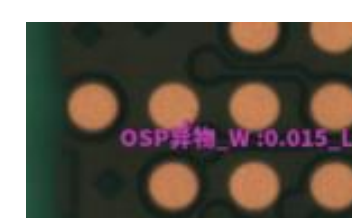
AI + traditional algorithms enable smart defect classification in real time



基板裂纹
Substrate crack



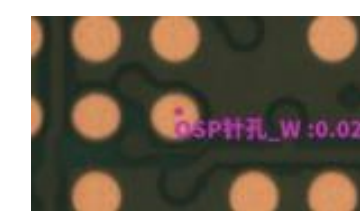
铜露出
Copper exposure



OSP异物
OSP contamination



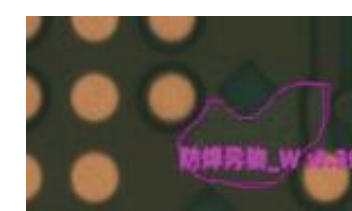
OSP变色
OSP discoloration



OSP针孔
OSP pinhole



金面伤痕
Gold surface scratch

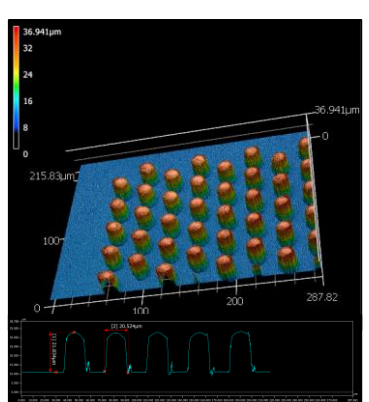


焊膏污染
Solder mask
contamination



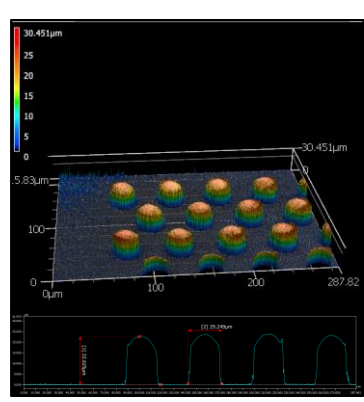
MIC孔白化
MIC hole whitening

3D/2D Bump Metrology



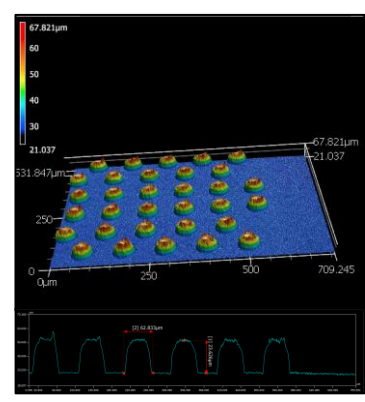
D=20.5μm
H=21.8μm
Pitch=36μm

SRO 14μm



D=29.2μm
H=22.6μm
Pitch=55μm

SRO 21μm

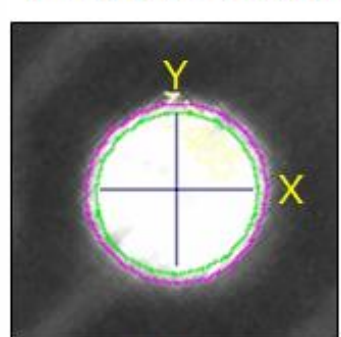


D=62.8μm
H=23.6μm

SRO 35μm

Various bump shapes and orientations

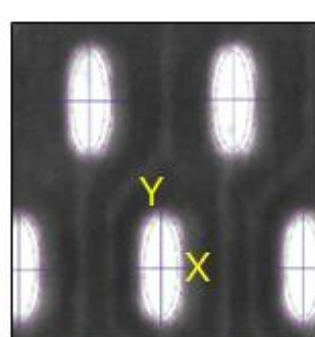
Measurement Direction



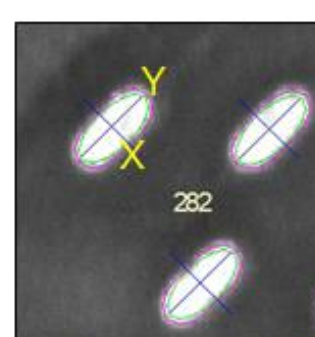
Circle post



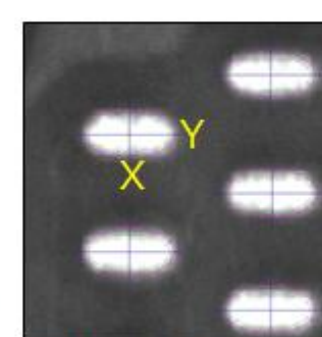
Circle IOP post



Oblong post(0°)



Oblong post(45°)



Oblong post(90°)

Key Specifications

2D AI+AVI Specification

Detectable Size	50 × 50 ~ 350 × 300 mm (supports dual-strip feeding)
Visual Parameter	CCD: Front side: 2.5 μm resolution / Back side: 5 μm resolution (optional); 16K color high-speed line scan; Robust Light Source
Defect Type	Discoloration, cracks, exposed copper, scratches, foreign matter, dents, notches etching defects, contamination, etc

3D Bump Inspection Specification

FOV	9.6mm
Min. Bump Size	20μm
Min. Bump Pitch	1.4x bump height
3D Resolution	5μm
2D Resolution	1.83μm
Application	C4 area bump measurement Bump height, bump diameter, bump coplanarity, etc.
Detection Range	CSP FC CSP Strip
Functions	Real-time yield monitoring+statistical data analysis+VRS (AIW) such as Mes Link, etc. Review workstations reduced to 0~1 units